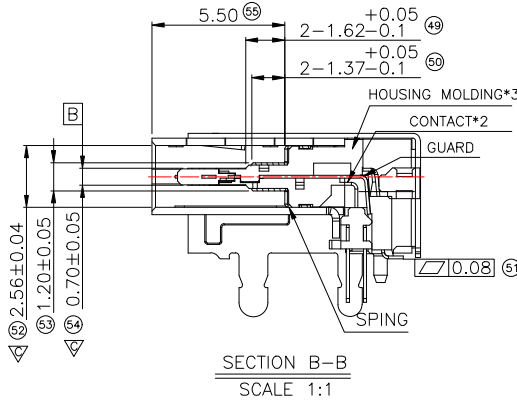
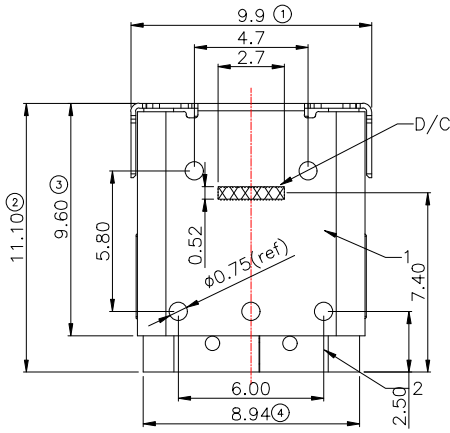


MAPX	MODIFICATION	DATE	DRAW	APPROVE



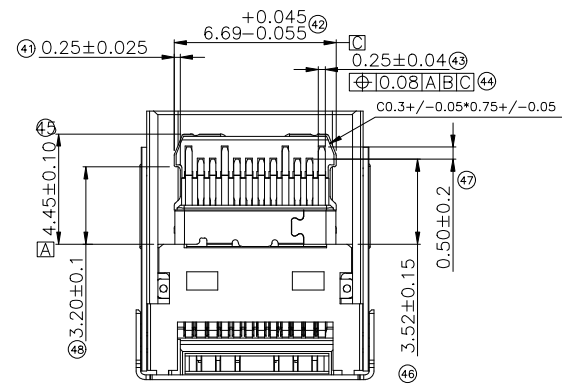
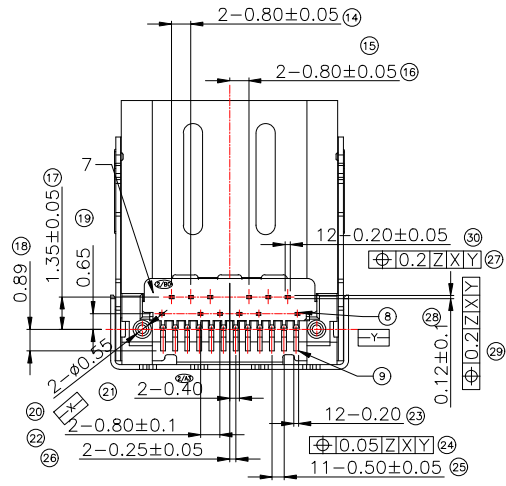
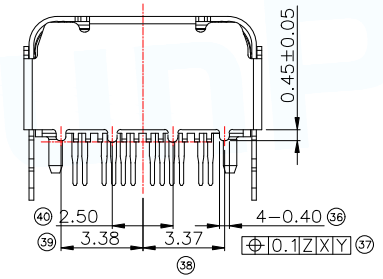
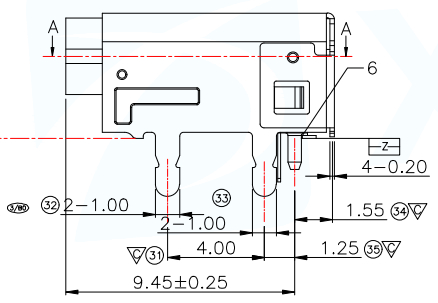
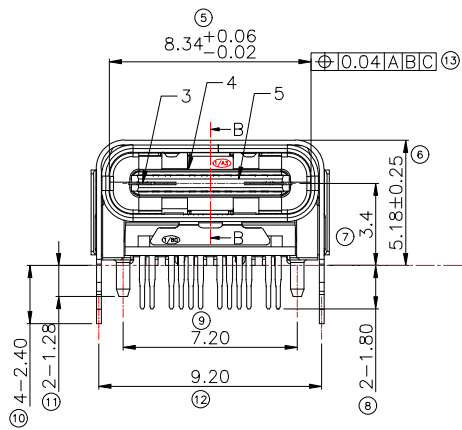
MATERIAL(材料):
 1.HOUSING: LCP, GLASS FIBER FILLED, BK
 胶壳: LCP ,GLASS FIBER FILLED, 黑色
 2.CONTACT: COPPY ALLOY (t=0.12mm).
 端子: COPPY ALLOY T=0.12mm
 3.GUARD PLATE:STAINLESS STEEL T=0.12mm
 护板: 不锈钢 T=0.12mm
 4.SPING:STAINLESS STEEL T=0.10mm
 簧片: 不锈钢 T=0.10mm
 5.SHIELD: STAINLESS STEEL (t=0.30mm).
 铁壳: 不锈钢 (t=0.30mm)
 6. OUT SHIELD:
 STAINLESS STEEL (t=0.20mm).
 外壳: 不锈钢 (t=0.20mm)

FINISH(电镀):
 CONTACT:30u Pd/Ni+2u*AU PLATING ON CONTACT AREA
 MAT TIN 120u" MIN. PLATING ON SOLDER TAILS AREA
 80u" MIN. NICKEL UNDERPLATING OVER ALL
 端子: 接触区镀金, 焊接区雾锡120u" Min., 镍底80u" MIN
 SHELL: 80u" MIN NICKEL PLATING OVER ALL
 铁壳: 整体镀可焊锡80u" MIN

ELECTICAL(电气性能):
 1.CONTACT RESISTANCE: 40 Milliohm MAX.
 接触电阻: 40 Milliohm MAX.
 2.DIELECTRIC WITHSTANDING VOLTAGE: AC 100V/MINUTE
 耐电压: AC 100V/MINUTE
 3.INSULATION RESISTANCE: 100 Megohms MIN.
 绝缘电阻: 100 Megohms MIN

MECHANICAL(机械性能):
 1.MATING FORCE: 5-20N MAX.
 插入力: 5-20N MAX.
 2.UNMATING FORCE: 8-20N MIN.
 拔出力: 8-20N MIN
 3.DURABILITY:10000 CYCLES
 耐久: 10000次

Marked "XX" should be FAI DIM,
 标记 "XX" 是FAI
 Marked " " should be major Control and first inspection DIM.
 标记 " " 是首件检验尺寸



SECTION A-A
SCALE 1:1

9	UPPER CONTACT	12	C18400 R480	30u Pd/Ni+2u Au PLATING ON CONTACT AREA MAT TIN 120u" MIN PLATING ON SOLDER TAILS AREA, 80u" MIN. NICKEL UNDERPLATING OVER ALL
8	LOWER CONTACT	12		
7	LOWER IM	1	LCP UL 94V-0	MOLDED COLOR: BLACK.
6	UPPER IM	1	LCP UL 94V-0	MOLDED COLOR: BLACK.
5	CENTER IM	1	LCP UL 94V-0	MOLDED COLOR: BLACK.
4	EMC	1	SUS304-1/2H	CLEAN
3	SHIELD PLATE	1	SUS304-1/2H	NICKEL PLATING OVER ALL.
2	INNER SHELL	1	SUS304-1/2H	CLEAN
1	OUTER SHELL	1	SUS304-1/2H	NICKEL PLATING ONLY AT TAIL, Au AT TABS AND SOLDER TAIL.
NO	DESCRIPTION	QTY.	MATFRIAI	TRFATFMT

MANUFACTURE DWG

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: .X:±0.50 .XX:±0.10

ANGLES: X':±2' .X':±1' .XX':±0.5°

CUSTOMER COPY

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd

TITLE: USB C TYPE 24P母座 垫高3.4

PAR TYPEC-505DDW-ACP24

DWN

CHKD

APVD

SCALE:1:1

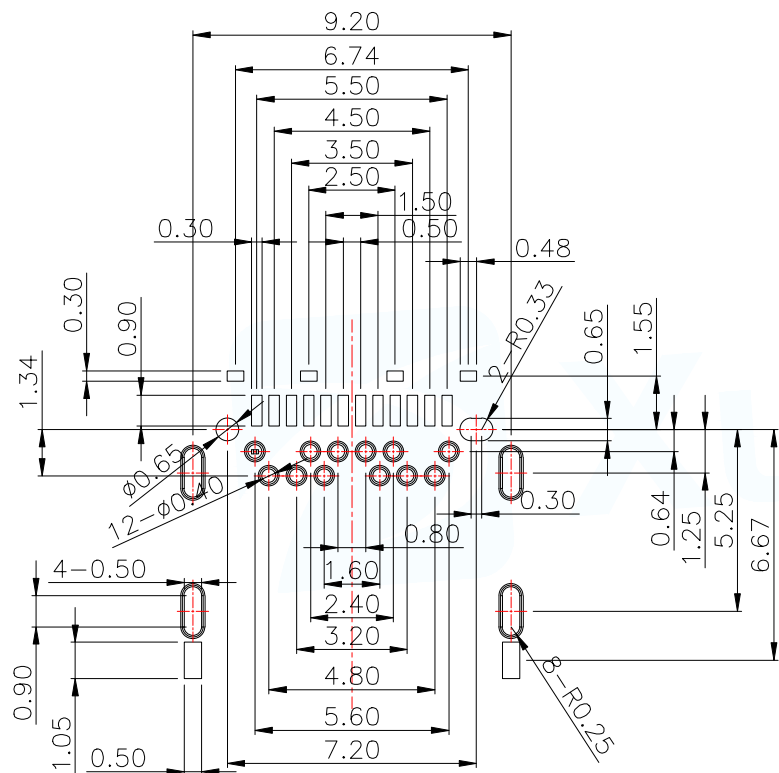
UNIT:MM

SIZE:A4

SHEET:1F1

REV:A

MAPX	MODIFICATION	DATE	DRAW	APPROVE



RECOMMENDED P.C.B LAYOUT(COMPONENT SIDE)

PCB THICKNESS:2.0±0.05mm

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use(SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use(SBU)	B5	CC2	Configuration Channel
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

MANUFACTURE DWG



UNLESS OTHERWISE SPECIFIED TOLERANCES



TITLE:
USB C TYPE 24P母座 规格3.4

DECIMALS:	ANGLES:
X.:±0.50	X'.:±2°
.X.:±0.30	.X'.:±1°
.XX.:±0.10	.XX'.:±0.5°

PAR	TYPEC-505DDW-ACP24
DWN	
CHKD	
APVD	
SCALE1:1	UNIT:MM
SIZE:A4	SHEET:1F1
CUSTOMER COPY	REV:A